

ABSTRACT

A cover tape for packaging electronic components that causes no contamination of sealing bar by the outflow of cushion layer and attains superior adhesion characteristic with the carrier tape is provided.

A cover tape for packaging electronic components heat-sealable to a carrier tape for packaging electronic components, comprising

at least a base layer, a cushion layer formed of resin A, a heat-seal following layer formed of resin B and a heat-sealing layer laminated in this order; wherein

Vicat softening temperature T_a of said resin A measured in accordance with ISO 306 (rate of temperature increase: 50°C/hour, load: 10N) and Vicat softening temperature T_b of said resin B measured in accordance with ISO 306 (rate of temperature increase: 50°C/hour, load: 10N) satisfy the Relational Expression 1 below; and

thickness of said heat-seal following layer is not smaller than 2 μm and not larger than 15 μm :

Relational Expression 1: $T_a - T_b \geq 3(^{\circ}\text{C})$.